

北京子航达辉电子有限公司

专业从事各类散热器/模组和DC风扇的研发设计，
生产和销售



专业从事各类散热模组和DC风扇的研发设计，生产和销售

C 公司人文 Company culture

社会责任

以人为本，重视环保自然，
为相关方创造更高价值

核心价值观

坚守契约 专注项目 奋斗不息
创造价值 共享成果 持续经营

品牌愿景

成为优秀的散热方案服务商，创民族品牌

文化理念

奋斗改变未来

企业使命

为中国互联网信息安全提供保障



CNC车间&冲压车间 CNC Workshop & Stamping Workshop

公司配置有生产散热模组的全部制程，有冲压、CNC、铲齿、回流焊、电镀、抗氧化、测试封装等制程，并下辖热导管、均温板（VC）等散热部件的生产制造。

公司研发设计人员30多人，从事散热研发设计均有超过10年以上工作经验。

通过了ISO9001质量管理体系和 ISO14001环境管理体系认证。采用标准化生产手段，实施规范化操作，确保产品质量长期稳定。

L 实验设备 laboratory equipment

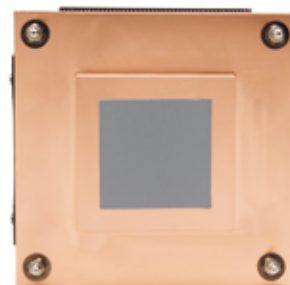
航达辉的测试和验证旨在确保产品和解决方案满足应用要求并符合行业标准。

航达辉承诺提供创新的问题解决方案以及测试服务，确保全面进行产品验证。



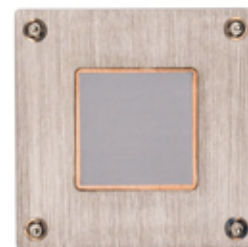
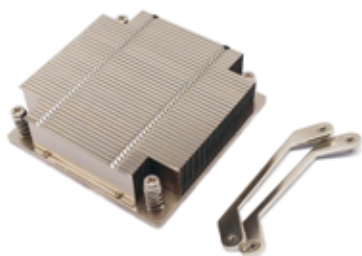
资质证书 CONSTRUCTION QUALIFICATION CERTIFICATE

H11



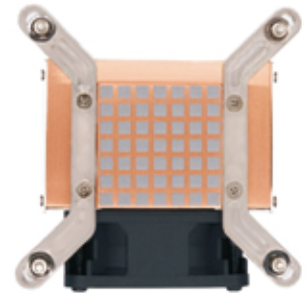
型号 (Model)	00018367
处理器架构(CPU Socket)	Intel Socket 115X ILM
机箱架构(Solution)	1U Server and Up(Active)
尺寸 (Dimensions)	89.6 x 89.6 x 27.8 mm
功耗 (TDP)	125W
材质 (Material)	Cu Skiving Fin + 7515 Blower
导热膏 (Thermal Grease)	BN-G560 Pre-Applied

H13



型号 (Model)	00018057
处理器架构(CPU Socket)	Intel Socket 115X ILM
机箱架构(Solution)	1U Server and Up(Passive)
尺寸 (Dimensions)	90.0 x 90.0 x 28.0 mm
功耗 (TDP)	95W
材质 (Material)	AL Base + Cu Block+ AL Fin + 2HP
导热膏 (Thermal Grease)	ShinEtsu X23-7762 Pre-Applied

H25



型号 (Model)	00018066
处理器架构(CPU Socket)	Intel Socket 115X ILM
机箱架构(Solution)	2U Server and Up(Active)
尺寸 (Dimensions)	91.0 x 90.0 x 67.3 mm
功耗 (TDP)	125W
材质 (Material)	Cu Base + AL Fin + 6025 Fan
导热膏 (Thermal Grease)	ShinEtsu X23-7762 Pre-Applied

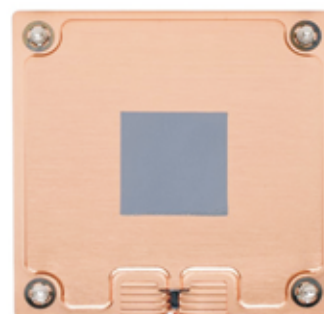
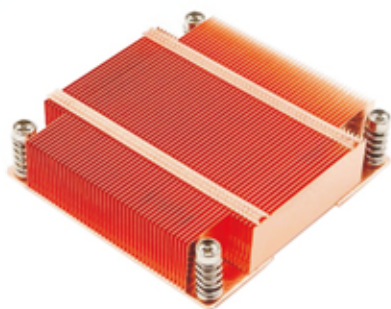
A3



型号 (Model)	00018902
处理器架构(CPU Socket)	Intel Socket 115X ILM
机箱架构(Solution)	4U Server and Up(Active)
尺寸 (Dimensions)	133.0 x 73.0 x 158.0 mm
功耗 (TDP)	165W
材质 (Material)	AL Base + Cu Block + AL Fin + 5HP + 12025 Fan
导热膏 (Thermal Grease)	ShinEtsu X23-7762 Pre - Applied

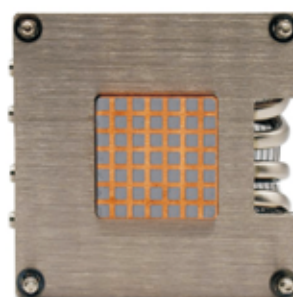
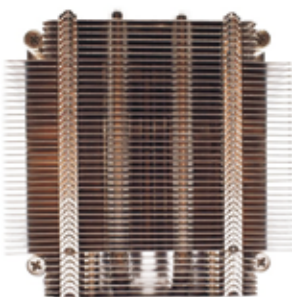
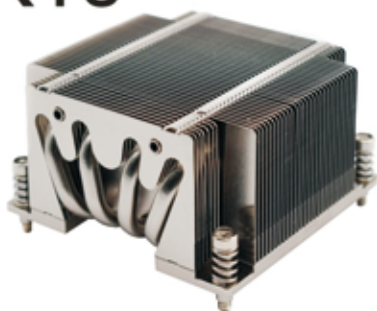
2011Square

K12



型号 (Model)	00018913
处理器架构(CPU Socket)	Intel Socket 2011 Square ILM
机箱架构(Solution)	1U Server and Up (Passive)
尺寸 (Dimensions)	90.0 x 90.0 x 23.2 mm
功耗 (TDP)	130W
材质 (Material)	VC + Cu Fin
导热膏 (Thermal Grease)	ShinEtsu X23-7783D Pre - Applied

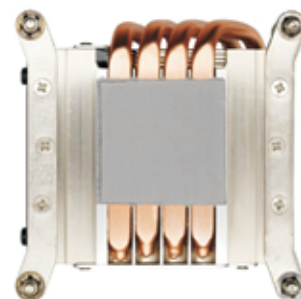
K15



型号 (Model)	00018065
处理器架构(CPU Socket)	Intel Socket 2011 Square ILM
机箱架构(Solution)	1.5U Server and Up(Passive)
尺寸 (Dimensions)	90.0 x 90.0 x 49.5 mm
功耗 (TDP)	130W
材质 (Material)	Cu Base+ AL Fin + 4HP
导热膏 (Thermal Grease)	ShinEtsu X23-7762 Pre - Applied

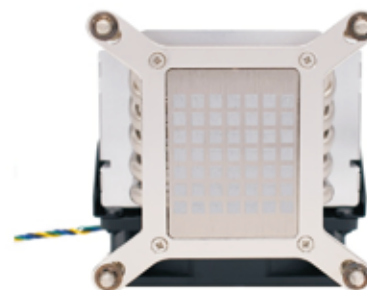
2011Square

K6



型号 (Model)	00018064
处理器架构(CPU Socket)	Intel Socket 2011 Square ILM
机箱架构(Solution)	2U Server and Up (Active)
尺寸 (Dimensions)	89.5 x 89.5 x 69.0 mm
功耗 (TDP)	165W
材质 (Material)	AL Base+AL Fin+HP + 6025 Fan
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

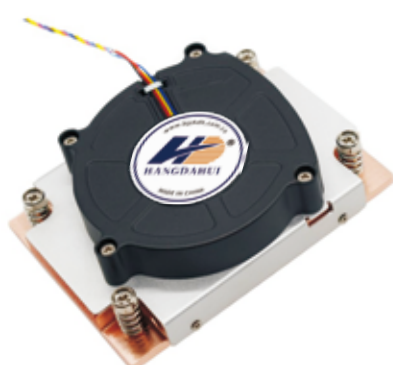
K3



型号 (Model)	00018059
处理器架构(CPU Socket)	Intel Socket 2011 Square ILM
机箱架构(Solution)	3U Server and Up (Active)
尺寸 (Dimensions)	109.95 x 95 x 127 mm
功耗 (TDP)	205W
材质 (Material)	AL Base +Cu Block+ AL Fin + 5HP + 9225 Fan
导热膏 (Thermal Grease)	ShinEtsu X23-7762 Pre - Applied

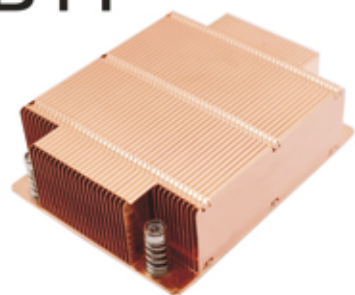
2011Narrow

B16



型号 (Model)	00018903
处理器架构(CPU Socket)	Intel Socket 2011 Narrow ILM
机箱架构(Solution)	1U Server and Up(Active)
尺寸 (Dimensions)	108.0 x 80.0 x 27.8 mm
功耗 (TDP)	205W
材质 (Material)	Cu Skiving Fin + 8015 Blower
导热膏(Thermal Grease)	ShinEtsuX23 - 7783D Pre - Applied

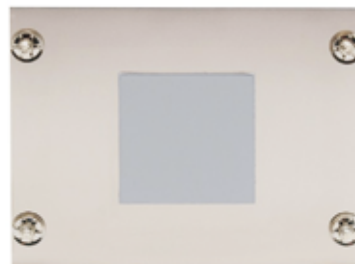
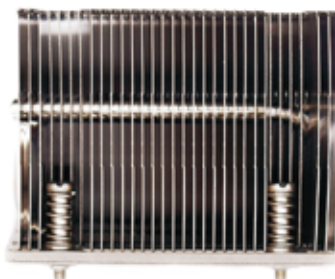
B11



型号 (Model)	00018904
处理器架构(CPU Socket)	Intel Socket 2011 Narrow ILM
机箱架构(Solution)	1U Server and Up(Passive)
尺寸 (Dimensions)	107.0 x 82.0 x 25.0 mm
功耗 (TDP)	145W
材质 (Material)	VC + Cu Fin
导热膏(Thermal Grease)	ShinEtsu X23-7783D Pre - Applied

2011Narrow

B2



型号 (Model)	00018058
处理器架构(CPU Socket)	Intel Socket 2011 Narrow ILM
机箱架构(Solution)	2U Server and Up(Passive)
尺寸 (Dimensions)	104.0 x 80.0 x 64.3 mm
功耗 (TDP)	145W
材质 (Material)	AL Base + Cu Block +AL Fin + 3HP
导热膏 (Thermal Grease)	BN-G620 Pre - Applied

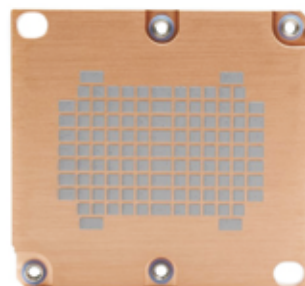
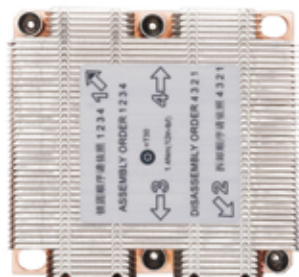
B3



型号 (Model)	00018912
处理器架构(CPU Socket)	Intel Socket 2011 Narrow ILM
机箱架构(Solution)	3U Server and Up(Passive)
尺寸 (Dimensions)	105.0 x 70.0 x 98.5 mm
功耗 (TDP)	165W
材质 (Material)	AL Base + Cu Block +AL Fin + 4HP
导热膏 (Thermal Grease)	ShinEtsu X23-7783D Pre - Applied

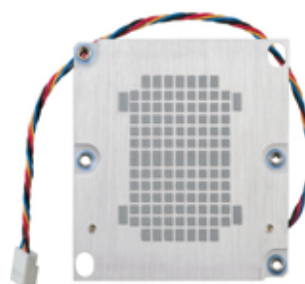
3647Square

P1



型号 (Model)	00018911
处理器架构(CPU Socket)	Intel FCLGA 3647 Square ILM
机箱架构(Solution)	1U Server and Up(Passive)
尺寸 (Dimensions)	91.0 x 88.0 x 25.5 mm
功耗 (TDP)	145W
材质 (Material)	Cu Base + AL Fin + 3HP
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

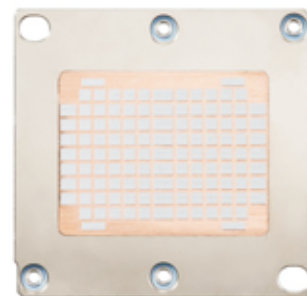
P21



型号 (Model)	00018914
处理器架构(CPU Socket)	Intel FCLGA 3647 Square ILM
机箱架构(Solution)	2U Server and Up(Active)
尺寸 (Dimensions)	91.0 x 85.0 x 64.0 mm
功耗 (TDP)	145W
材质 (Material)	AL Extrusion Fin+ 6025 Fan
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

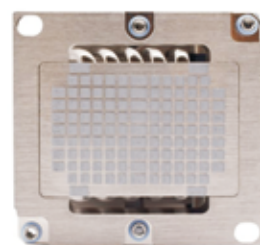
3647Square

P22



型号 (Model)	00018060
处理器架构(CPU Socket)	Intel FCLGA 3647 Square ILM
机箱架构(Solution)	2U Server and Up(Active)
尺寸 (Dimensions)	91.0 x 88.0 x 64.0 mm
功耗 (TDP)	205W
材质 (Material)	AL Base + Cu Block + AL Fin + 4HP + 6025 Fan
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

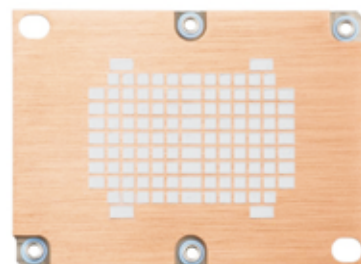
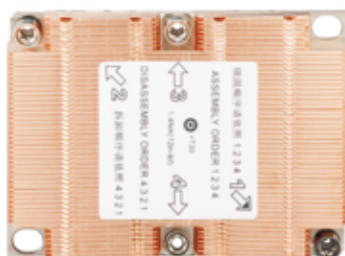
P3



型号 (Model)	00018777
处理器架构(CPU Socket)	Intel FCLGA 3647 Square ILM
机箱架构(Solution)	4U Server and Up(Active)
尺寸 (Dimensions)	108.0 x 95.0 x 126.3 mm
功耗 (TDP)	305W
材质 (Material)	AL Base + Cu Block + AL Fin + 5HP+ 9225 Fan
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

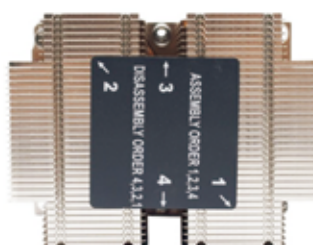
3647Narrow

F11



型号 (Model)	00018909
处理器架构(CPU Socket)	Intel FCLGA 3647 Narrow ILM
机箱架构(Solution)	1U Server and Up(Passive)
尺寸 (Dimensions)	108.0 x 78.0 x 25.5 mm
功耗 (TDP)	165W
材质 (Material)	AL Base + Cu Block + Cu Fin + Heatpipe
导热膏(Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

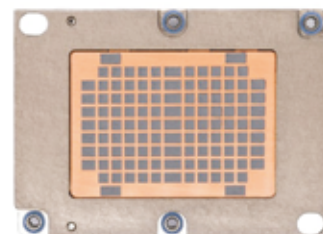
F2



型号 (Model)	00018071
处理器架构(CPU Socket)	Intel FCLGA 3647 Narrow ILM
机箱架构(Solution)	2U Server and Up(Passive)
尺寸 (Dimensions)	108.0 x 78.0 x 64.0 mm
功耗 (TDP)	205W
材质 (Material)	AL Base + Cu Block + AL Fin + 4HP
导热膏(Thermal Grease)	ShinEtsu X23-7783D Pre - Applied

3647Narrow

F23



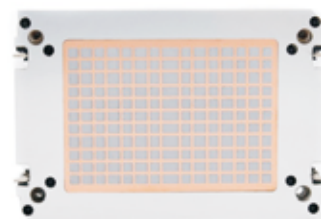
型号 (Model)	000180068
处理器架构(CPU Socket)	Intel FCLGA 3647 Narrow ILM
机箱架构(Solution)	2U Server and Up(Active)
尺寸 (Dimensions)	108.0 x 78.0 x 64.0 mm
功耗 (TDP)	205W
材质 (Material)	AL Base + Cu Block +AL Fin + 4HP + 6025 Fan
导热膏 (Thermal Grease)	ShinEtsu X23-7783D Pre - Applied

F3



型号 (Model)	00018776
处理器架构(CPU Socket)	Intel FCLGA 3647 Narrow ILM
机箱架构(Solution)	4U Server and Up(Active)
尺寸 (Dimensions)	108.0 x 92.5 x 126.3 mm
功耗 (TDP)	305W
材质 (Material)	AL Base + Cu Block +AL Fin + 6HP+ 9225 Fan
导热膏 (Thermal Grease)	ShinEtsu X23-7783D Pre - Applied

W1



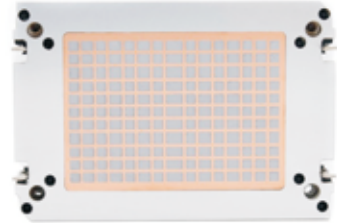
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处理器架构(CPU Socket)	Intel FCLGA 4189 Narrow ILM (Whitley)
机箱架构(Solution)	1U Server and Up (Passive)
尺寸 (Dimensions)	113.0 x 78.0 x 24.6 mm
功耗 (TDP)	205W
材质 (Material)	AL Base + Cu Block +AL Fin + 4HP
导热膏 (Thermal Grease)	ShinEtsu X23 7783D Pre - Applied

W11



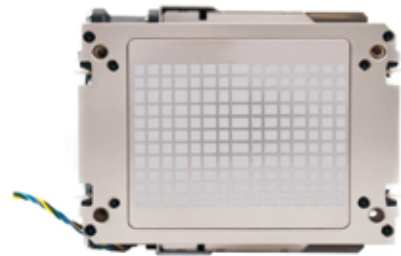
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处理器架构(CPU Socket)	Intel FCLGA 4189 Narrow ILM (Whitley)
机箱架构(Solution)	1U Server and Up (Active)
尺寸 (Dimensions)	113.0 x 80.0 x 27.8 mm
功耗 (TDP)	250W
材质 (Material)	VC+ Cu Fin + 8015 Blower
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

W2



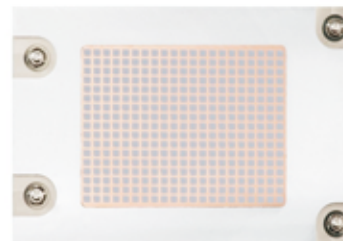
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处理器架构(CPU Socket)	Intel FCLGA 4189 Narrow ILM (Whitley)
机箱架构(Solution)	2U Server and Up (Passive)
尺寸 (Dimensions)	113.0 x 78.0 x64.0mm
功耗 (TDP)	250W
材质 (Material)	AL Base + Cu Block +AL Fin + 5HP
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

W3



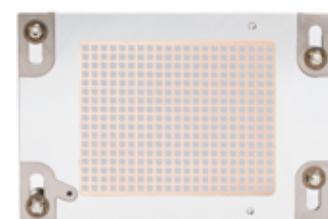
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处理器架构(CPU Socket)	Intel FCLGA 4189 Narrow ILM (Whitley)
机箱架构(Solution)	3U Server and Up (Active)
尺寸 (Dimensions)	113.0 x 95.0 x126.3mm
功耗 (TDP)	305W
材质 (Material)	AL Base + Cu Block +AL Fin + 6HP + 9225 Fan
导热膏 (Thermal Grease)	ShinEtsu X23 - 7783D Pre - Applied

S1



型号 (Model)	00018056
处理器架构(CPU Socket)	AMD SP3ILM
机箱架构(Solution)	1U Server and Up(Passive)
尺寸 (Dimensions)	120.0 x 80.0 x 28.5 mm
功耗 (TDP)	180W
材质 (Material)	AL Base + Cu Block + AL Fin + 3HP
导热膏 (Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

S2



型号 (Model)	00018905
处理器架构(CPU Socket)	AMD SP3ILM
机箱架构(Solution)	2U Server and Up(Passive)
尺寸 (Dimensions)	120.0 x 80.0 x 63.5 mm
功耗 (TDP)	240W
材质 (Material)	AL Base + Cu Block + AL Fin + 4HP
导热膏 (Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

S22



型号 (Model)	00018061
处理器架构(CPU Socket)	AMD SP3 ILM
机箱架构(Solution)	2U Server and Up(Active)
尺寸 (Dimensions)	120.0 x 80.0 x 63.5 mm
功耗 (TDP)	240W
材质 (Material)	AL Base + Cu Block +AL Fin + 4HP + 6025 Fan
导热膏 (Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

S3



型号 (Model)	00018753
处理器架构(CPU Socket)	AMD SP3 ILM
机箱架构(Solution)	3U Server and Up(Active)
尺寸 (Dimensions)	120.0 x 95.0 x 126.3 mm
功耗 (TDP)	305W
材质 (Material)	AL Base + Cu Block +AL Fin + 6HP + 9225 Fan
导热膏 (Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

4028



Model	Rated	Rated	Input	Rated	Maximum	Maximum	Sound
	Voltage	Current	Power	Speed	AirFlow	Pressure	Level
	V	Amp	W	rpm	CFM	mmH ₂ O	dB(A)
HD4028M12B	12	0.25	3.00	12000	16.15	18.77	42.80
HD4028H12B	12	0.40	4.80	15000	20.19	29.33	47.64
HD4028U12B	12	0.80	9.60	20000	22.36	50.50	53.89

6025



Model	Rated	Rated	Input	Rated	Maximum	Maximum	Sound
	Voltage	Current	Power	Speed	AirFlow	Pressure	Level
	V	Amp	W	rpm	CFM	mmH ₂ O	dB(A)
HD6025M12B	12	0.48	5.76	6800	38.69	13.94	43.55
HD6025H12B	12	0.65	7.80	9000	50.82	24.42	59.62

12025



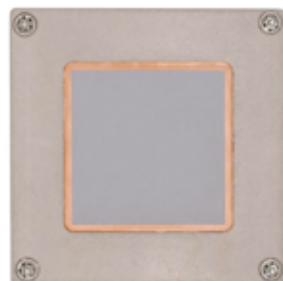
Model	Rated	Rated	Input	Rated	Maximum	Maximum	Sound
	Voltage	Current	Power	Speed	AirFlow	Pressure	Level
	V	Amp	W	RPM	CFM	mmH ₂ O	dB(A)
HD12025L12B	12	0.15	1.80	1500	73.00	1.80	26.50
HD12025M12B	12	0.35	4.20	2000	97.33	3.11	32.74
HD12025H12B	12	0.40	4.80	2500	121.67	4.86	37.59

7515 Blower



Model	Rated	Rated	Input	Rated	Maximum	Maximum	Sound
	Voltage	Current	Power	Speed	Air Flow	Pressure	Level
	V	Amp	W	RPM	CFM	mmH ₂ O	dB(A)
HB7515L12B	12	0.25	3.00	4000	8.93	17.70	50.02
HB7515M12B	12	0.38	4.56	5000	11.90	23.60	55.00
HB7515H12B	12	0.60	7.20	6000	14.87	29.50	58.95

G11



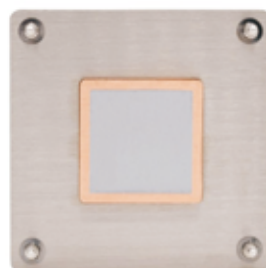
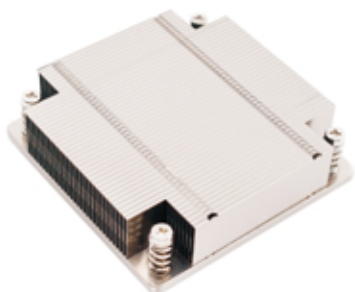
型号 (Model)	00018915
处理器架构(CPU Socket)	兆芯 KH-38800D
机箱架构(Solution)	1U Server and Up (Passive)
尺寸 (Dimensions)	90.0 x 90.0 x 27.0mm
功耗 (TDP)	120W
材质 (Material)	AL Base + Cu Block + Cu Fin + 2HP
导热膏 (Thermal Grease)	ShinEtsu X 23 - 7783D Pre - Applied

G12



型号 (Model)	00018916
处理器架构(CPU Socket)	飞腾 FT-2500+
机箱架构(Solution)	1U Server and Up (Passive)
尺寸 (Dimensions)	120.0 x 80.0 x 23.8mm
功耗 (TDP)	120W
材质 (Material)	AL Base + Cu Block + AL Fin + 3HP
导热膏 (Thermal Grease)	ShinEtsu X 23 - 7762 Pre - Applied

G13



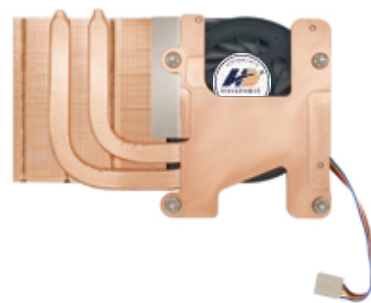
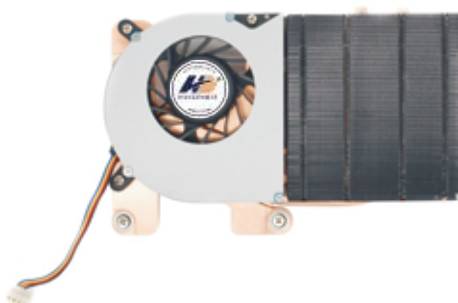
型号 (Model)	00018917
处理器架构(CPU Socket)	海光 HYGON-3100
机箱架构(Solution)	1U Server and Up (Passive)
尺寸 (Dimensions)	90.0 x 90.0 x 26.0mm
功耗 (TDP)	95W
材质 (Material)	AL Base + Cu Block + AL Fin + 3HP
导热膏 (Thermal Grease)	ShinEtsuX 23 - 7783D Pre - Applied

G15



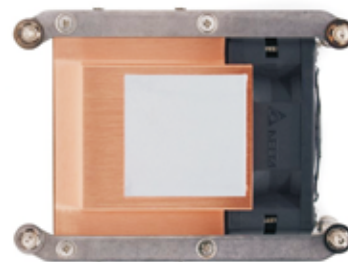
型号 (Model)	00018918
处理器架构(CPU Socket)	海光 HYGON-3100
机箱架构(Solution)	1U Server and Up (Passive)
尺寸 (Dimensions)	105.0 x 75.0 x 28.3mm
功耗 (TDP)	120W
材质 (Material)	AL Base + Cu Block + Cu Fin + 2HP
导热膏 (Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

G16



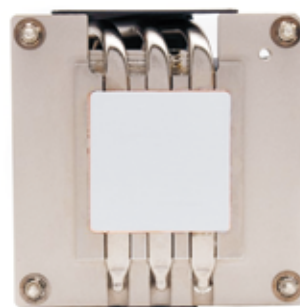
型号 (Model)	00018919
处理器架构(CPU Socket)	兆芯 KX - U6780A
机箱架构(Solution)	1U Server and Up (Active)
尺寸 (Dimensions)	163.45 x 103.2 x 27.8mm
功耗 (TDP)	75W
材质 (Material)	AL Base + Cu Block + Cu Fin + 2HP
导热膏 (Thermal Grease)	ShinEtsuX 23 - 7783D Pre - Applied

G22



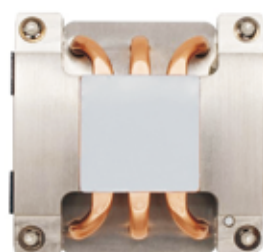
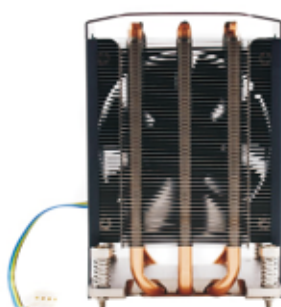
型号 (Model)	00018920
处理器架构(CPU Socket)	海光 HYGON - 3100
机箱架构(Solution)	2U Server and Up (Active)
尺寸 (Dimensions)	99.0 x 74.0 x 65.5mm
功耗 (TDP)	125W
材质 (Material)	Cu Base + AL Fin + 6025 Fan
导热膏 (Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

G25



型号 (Model)	00018921
处理器架构(CPU Socket)	海光HYGON- 3100
机箱架构(Solution)	2U Server and Up (Active)
尺寸 (Dimensions)	85.6 x 83.0 x 68.5mm
功耗 (TDP)	125W
材质 (Material)	AL Base + Cu Block + AL Fin + 3HP + 6025 Fan
导热膏(Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

G31



型号 (Model)	00018922
处理器架构(CPU Socket)	海光HYGON- 3100
机箱架构(Solution)	4U Server and Up (Active)
尺寸 (Dimensions)	85.0 x 85.0 x 124.5mm
功耗 (TDP)	165W
材质 (Material)	AL Base + Cu Block + AL Fin + 3HP + 8025 Fan
导热膏(Thermal Grease)	Dow Corning TC - 5218 Pre - Applied

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